

## C0603C100MATAC7411

**General Information** 

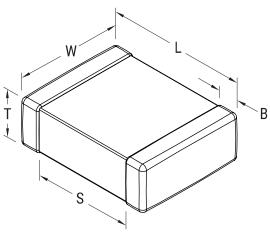
Series Style

SMD Comm X8G HT150C, Ceramic, 10 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm

SMD Comm X8G HT150C

SMD Chip





	Click here for the 3D model.	Description	SMD, MLCC, High Temperature, Ultra-Stable
T M		Features	High Temperature, Ultra-Stable
•		RoHS	Yes
		Termination	Tin
		Marking	No
		AEC-Q200	No
		Typical Component Weight	3.7 mg
		Shelf Life	78 Weeks
		MSL	1
mensions		Specifications	

Dimensions				
Chip Size	0603			
L	1.6mm +/-0.15mm			
W	0.8mm +/-0.15mm			
Т	0.8mm +/-0.07mm			
S	0.5mm MIN			
В	0.35mm +/-0.15mm			

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

Specifications				
Capacitance	10 pF			
Measurement Condition	1 MHz 1.0Vrms			
Tolerance	20%			
Voltage DC	250 VDC			
Dielectric Withstanding Voltage	625 VDC			
Temperature Range	-55/+150°C			
Temp. Coefficient	X8G			
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms			
Dissipation Factor	0.1% 1 MHz 1.0Vrms			
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours			
Insulation Resistance	100 GOhms			

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